

## 1ch Low Side Switch IC

## In-Vehicle 1ch Low Side Switch

BD1LB500 Series (BD1LB500EFJ-C BD1LB500FVM-C)

## Features

- Built-in overcurrent limiting circuit
- Built-in thermal shutdown circuit (TSD)
- Built-in open load detection circuit (at output OFF)
- Enables direct control from CMOS logic ICs, etc.
- Low standby current
- Built-in under voltage lock out circuit
- Built-in diagnostic output (ST) terminal
- Low ON resistance  $R_{DS(ON)}=350\text{m}\Omega$ (Typ) ( $V_{DD}=IN=5\text{V}$ ,  $T_a=25^\circ\text{C}$ ,  $I_{OUT}=0.25\text{A}$ )
- Built-in overvoltage protection(active clamp) for output circuit
- Monolithic power IC in which the control unit (CMOS) and power MOS FET are incorporated into one chip
- 1ch low side switch for driving mechanical relay coil
- AEC-Q100 Qualified<sup>(1)</sup>  
(1) Grade1

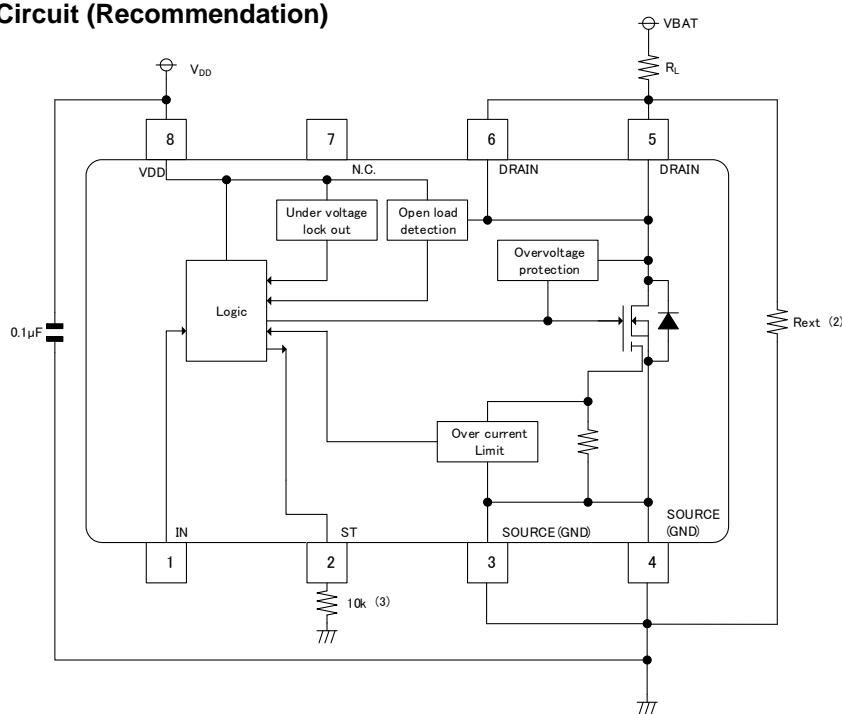
## Overview

BD1LB500 Series is an in-vehicle 1ch low side switch. This switch builds in the overcurrent limiting circuit, thermal shutdown circuit, open load detection circuit and under voltage lock out circuit. It also provides the diagnostic output circuit when an abnormality is detected.

## Application

- In-vehicle application (Air conditioners, body devices, meters, etc.)

## Basic Application Circuit (Recommendation)



(2) When the open detection function is required, an external resistance must be added between DRAIN terminal and SOURCE terminal.

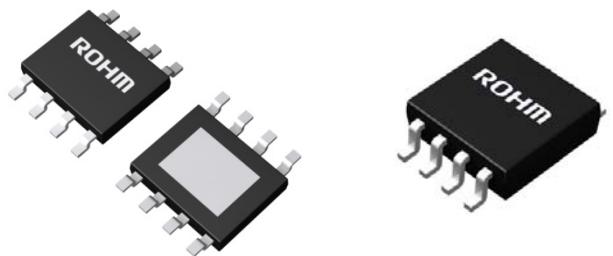
(3) It is necessary to detect unusual state(ST terminal is low) when VDD terminal is opened.

When ST pin is not used, it can be open.

## Specifications

Operating voltage range	3.5V to 5.5V
ON resistance (25°C, Typ.)	350mΩ
Overcurrent limitation (Typ.)	1.50A
Active clamp energy (25°C)	25mJ

## Package

HTSOP-J8  
MSOP84.90mm x 6.00mm x 1.00mm  
2.90mm x 4.00mm x 0.90mm

HTSOP-J8

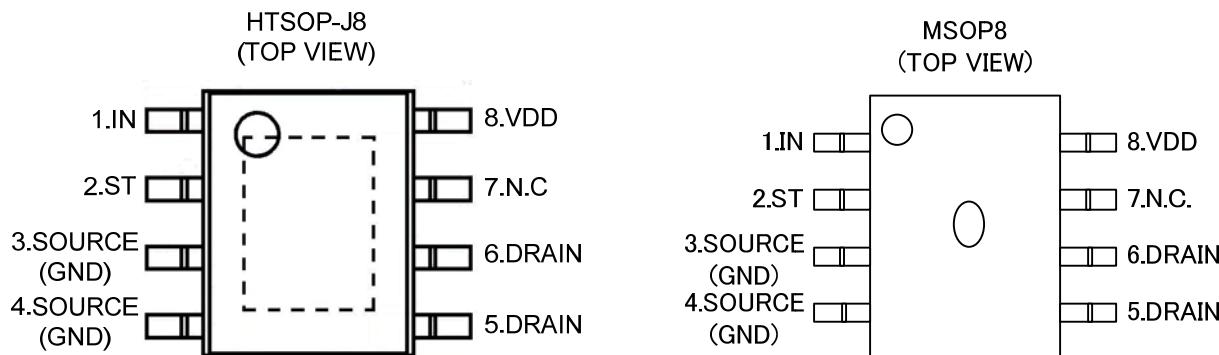
MSOP8

## Pin Descriptions

Pin No.	Symbol	Function
1	IN	Input terminal; a pull down resistor is connected internally.
2	ST	Self-diagnostic output terminal; outputs "L" at detection of overcurrent, at open (IN=0V), and in the overheat state. See the truth table. It is structured as COMS inverter output circuit.
3,4	SOURCE (GND)	Ground terminal
5,6	DRAIN	Output terminal; limits output current to protect IC when load is short-circuited and current exceeding the overcurrent detection value (0.8A Min) flows to the output terminal.
7	N.C.	No Connect pin
8	VDD	Power supply terminal
Cooling Tab <sup>(1)</sup>	TAB	The heat radiation metal on the substrate is connected to the IC sub. Therefore, connect Cooling Tab to the external GND electrical potential (for HTSOP-J8 only).

(1)MSOP8 does not have Cooling Tab.

## Pin Configurations



Product Name	PKG	TSD function	ON resistance (25°C,Typ)
BD1LB500EFJ-C	HTSOP-J8	Self-restart	350mΩ
BD1LB500FVM-C			

## Absolute Maximum Ratings

Item	Symbol	Limit values	Unit
DRAIN-SOURCE voltage	$V_{DS}$	42 (internally limited)	V
Power supply voltage	$V_{DD}$	7	V
Diagnostic output voltage	$V_{ST}$	-0.3 to +7 <sup>(1)</sup>	V
Output current (DC)	$I_{OD}$	0.8 <sup>(2)</sup>	A
Output current (Pulse)	$I_{OP}$	Internally limited <sup>(3)</sup>	A
Input voltage	$V_{IN}$	-0.3 to +7 <sup>(1)</sup>	V
Power consumption	$P_d$	2.1(HTSOP-J8) <sup>(4)</sup>	W
		0.587(MSOP8) <sup>(5)</sup>	
Operating temperature range	$T_{opr}$	-40 ≤ $T_{opr}$ < +150	°C
Storage temperature range	$T_{stg}$	-55 to +150	°C
Maximum junction temperature	$T_{jmax}$	150	°C
Active clamp energy (single pulse)	$E_{AS}(25^{\circ}\text{C})$	25 <sup>(6)</sup>	mJ
	$E_{AS}(150^{\circ}\text{C})$	25 <sup>(7)(8)</sup>	mJ

## Operating Voltage Ratings

Item	Code	Limit values	Unit
Operating voltage range	$V_{DD}$	3.5 to 5.5	V

(1) The condition,  $V_{DD} > V_{IN}$ ,  $V_{ST}$  is required.

(2) The value must not exceed  $P_d$ .

(3) Internally limited by the overcurrent limiting circuit.

(4) When mounting PCB (70×70[mm], thickness 1.6[mm], copper foil area 70×70[mm], glass epoxy 2-layer substrate).

When using at  $T_a \geq 25^{\circ}\text{C}$ , power dissipation is reduced at 16.8mW/°C.

(5) When mounting PCB (70×70[mm], thickness 1.6[mm], copper foil area is Footprint only, glass epoxy single-layer substrate).

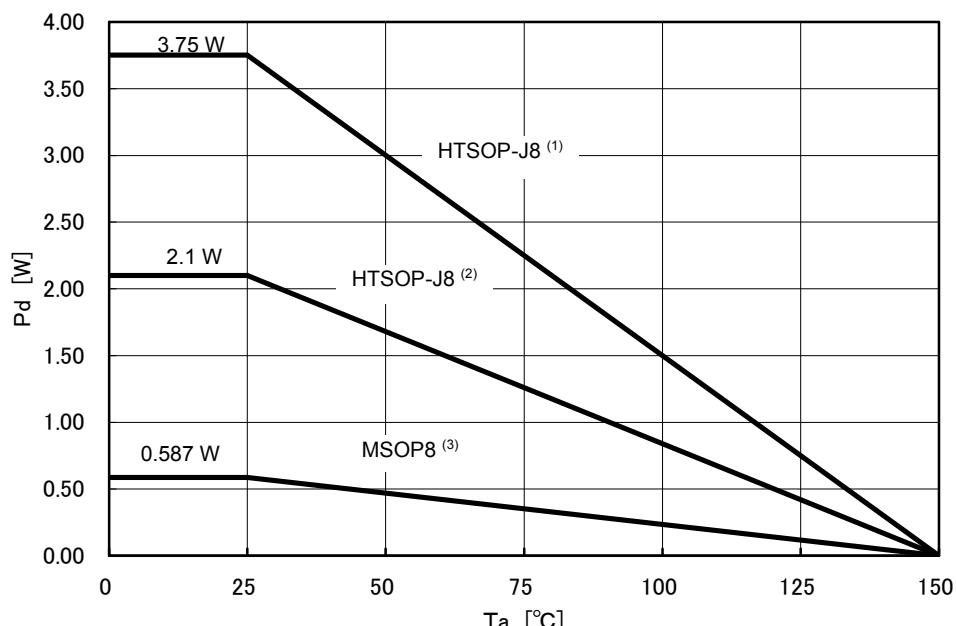
When using at  $T_a \geq 25^{\circ}\text{C}$ , power dissipation is reduced at 4.7mW/°C.

(6) Active clamp energy at  $T_{j(0)} = 25^{\circ}\text{C}$ , using single non-repetitive pulse of 0.4A

(7) Active clamp energy at  $T_{j(0)} = 150^{\circ}\text{C}$ , using single non-repetitive pulse of 0.4A

(8) Not 100% tested.

## Heat Dissipation Characteristics



(HTSOP-J8) (1) When mounting PCB (70×70[mm], thickness 1.6[mm], copper foil area 70×70[mm], glass epoxy 4-layer substrate)  
When using at  $T_a \geq 25^{\circ}\text{C}$ , power dissipation is reduced at 30mW/°C.

(2) When mounting PCB (70×70[mm], thickness 1.6[mm], copper foil area 70×70[mm], glass epoxy 2-layer substrate)  
When using at  $T_a \geq 25^{\circ}\text{C}$ , power dissipation is reduced at 16.8mW/°C.

(MSOP8) (3) When mounting PCB (70×70[mm], thickness 1.6[mm], copper foil area is Footprint only, glass epoxy single-layer substrate)  
When using at  $T_a \geq 25^{\circ}\text{C}$ , power dissipation is reduced at 4.7mW/°C.

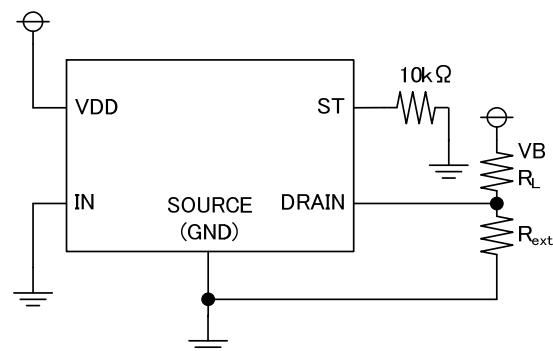
Electrical Characteristics ( $V_{DD}=3.5V$  to  $5.5V$ ,  $-40^{\circ}C \leq T_j \leq +150^{\circ}C$  unless otherwise is specified)

Item	Symbol	Limit values			Unit	Condition
		Min	Typ	Max		
[Power Supply Block]						
Standby current	$I_{DDS}$	—	0	10	$\mu A$	$V_{DD}=5V, V_{IN}=0V, V_B=12V, R_L=47\Omega$
Operating current	$I_{DD}$	—	0.5	1.0	mA	$V_{DD}=5V, V_{IN}=5V, V_B=12V, R_L=47\Omega$
Under voltage lock out threshold voltage	$V_{UVLO}$	—	2.5	3.0	V	
[Input Block]						
H level input voltage	$V_{TH1}$	—	—	$V_{DD} \times 0.8$	V	
L level input voltage	$V_{TH2}$	$V_{DD} \times 0.2$	—	—	V	
Input hysteresis	$V_{HYS}$	—	0.40	—	V	
High level input current	$I_{INH1}$	—	50	100	$\mu A$	$V_{IN}=5V$
Low level input current	$I_{INL}$	-1	0	1	$\mu A$	$V_{IN}=0V$
[Power MOS output]						
Output ON resistance	$R_{DS(ON)}$	—	350	450	$m\Omega$	$V_{IN}=5V, V_{DD}=5V, I_D=0.25A, T_j=25^{\circ}C$
	$R_{DS(ON)}$	—	570	750	$m\Omega$	$V_{IN}=5V, V_{DD}=5V, I_D=0.25A, T_j=150^{\circ}C$
Output leak current	$I_{L(OFF)}$	—	—	10	$\mu A$	$V_{IN}=0V, V_{DS}=12V, T_j=25^{\circ}C$
	$I_{L(OFF)}$	—	—	100	$\mu A$	$V_{IN}=0V, V_{DS}=12V, T_j=150^{\circ}C$
Switching time	$t_{ON}$	—	20	40	$\mu s$	$V_{DD}=5V, V_{IN}=0V/5V, R_L=47\Omega$
	$t_{OFF}$	—	20	40	$\mu s$	$V_{DD}=5V, V_{IN}=0V/5V, R_L=47\Omega$
Slew rate (at ON)	$dV/dt_{ON}$	0.5	1	2	V/ $\mu s$	$V_{DD}=5V, V_{IN}=0V/5V, R_L=47\Omega$
Slew rate (at OFF)	$-dV/dt_{OFF}$	0.5	1	2	V/ $\mu s$	$V_{DD}=5V, V_{IN}=0V/5V, R_L=47\Omega$
Output clamp voltage	$V_{CL}$	42	47	52	V	$V_{IN}=0V, I_{OUT}=-1mA$
[Diagnostic output]						
Diagnostic output voltage "L level"	$V_{STL}$	—	—	0.4	V	$V_{DD}=5V, V_{IN}=5V, I_{ST}=0.1mA$
Diagnostic output voltage "H level"	$V_{STH}$	4.88	—	—	V	$V_{DD}=5V, V_{IN}=0V, I_{ST}=-0.1mA$
Diagnostic output current "H level"	$I_{STH}$	—	—	10	$\mu A$	$V_{IN}=0V, V_{ST}=5.5V$

Electrical Characteristics ( $V_{DD}=3.5V$  to  $5.5V$ ,  $-40^{\circ}C \leq T_j \leq +150^{\circ}C$  unless otherwise is specified)

Item	Symbol	Rated value			Unit	Condition
		Min	Typ	Max		
[Protective circuit]						
Overcurrent detection current	$I_{OCP}$	0.8	1.5	2.5	A	$V_{IN}=5V$
Diagnostic output delay time	$t_{DHL}$	—	40	80	$\mu s$	$V_{DD}=5V, R_L=4\Omega$ to $\infty$
	$t_{DLH}$	—	320	640	$\mu s$	$V_{DD}=5V, R_L=\infty$ to $4\Omega$
Open load detection threshold voltage <sup>(1)</sup>	$V_{OPEN}$	1	2	3	V	$IN=0V$
Open load detection time	$t_{OPEN}$	100	300	900	$\mu s$	$IN=0V$

(1) To enable detection, an external resistance must be added between DRAIN terminal and SOURCE terminal.  
(Determine  $R_{ext}$  depending on  $R_L$ .)



## Definition

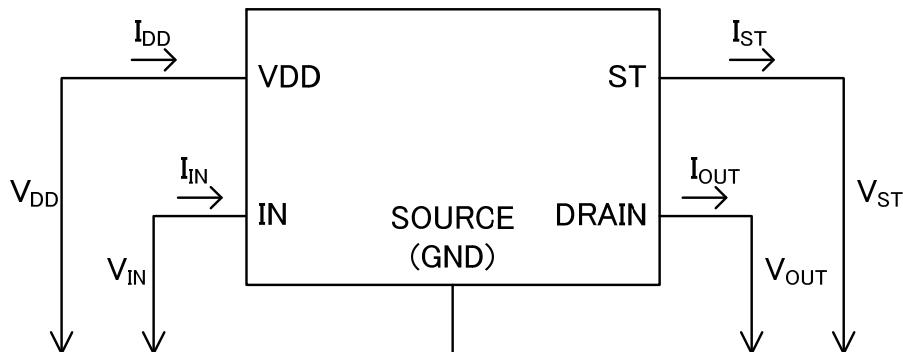
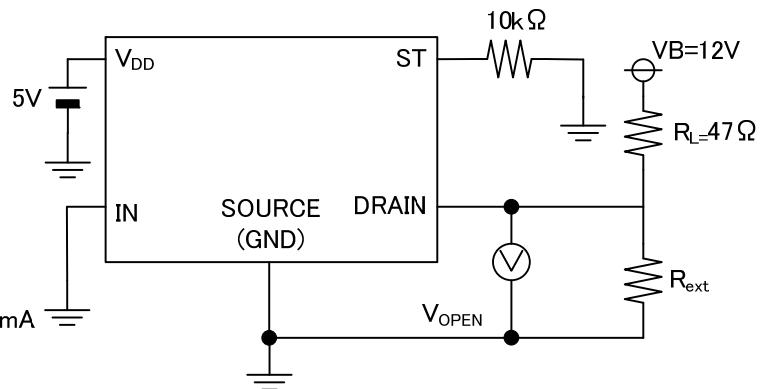
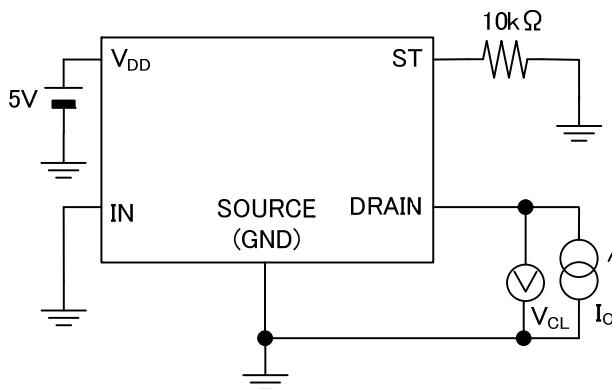
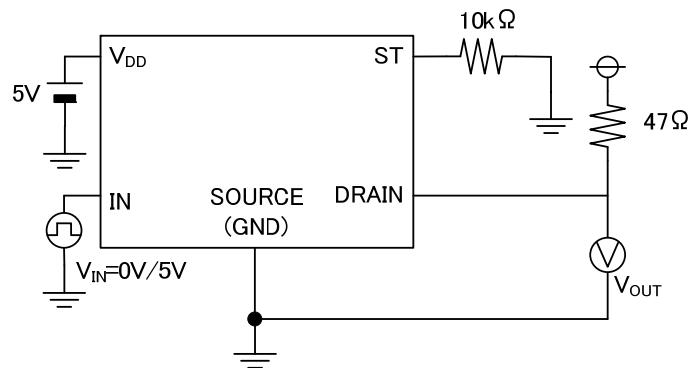
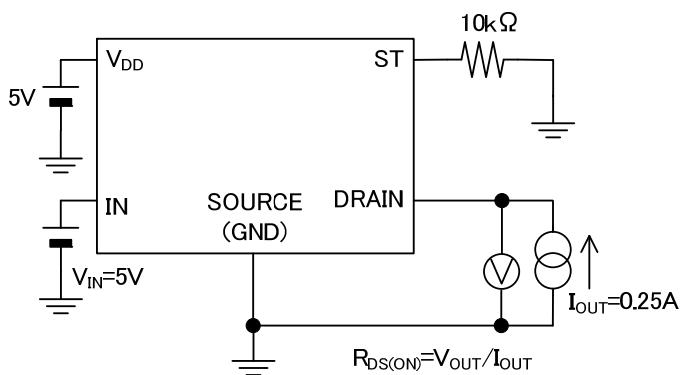


Figure 1. Definition

## Measuring Circuit Diagram



## Diagnostic Output Truth Table

V <sub>IN</sub>	T <sub>j</sub>	OUTPUT		Mode	V <sub>ST</sub>	Output state
		V <sub>OUT</sub>	I <sub>OUT</sub>			
H	T <sub>j</sub> ≤ 175°C(Typ)	-	I <sub>OUT</sub> < 1.5A(Typ)	Normal	H	ON
			I <sub>OUT</sub> ≥ 1.5A(Typ)	Overcurrent detection	L	OFF
	T <sub>j</sub> > 175°C(Typ)	-	-	Thermal shut down	L	OFF
L	-	H (3.0V or more)	-	Normal	H	OFF
		L (2.0V(Typ) or less)	-	Open load protection	L	OFF

Characteristic Data (Reference Data) ( $V_{DD}=5V$ ,  $IN=5V$ ,  $T_j=25^{\circ}C$  unless otherwise is specified)

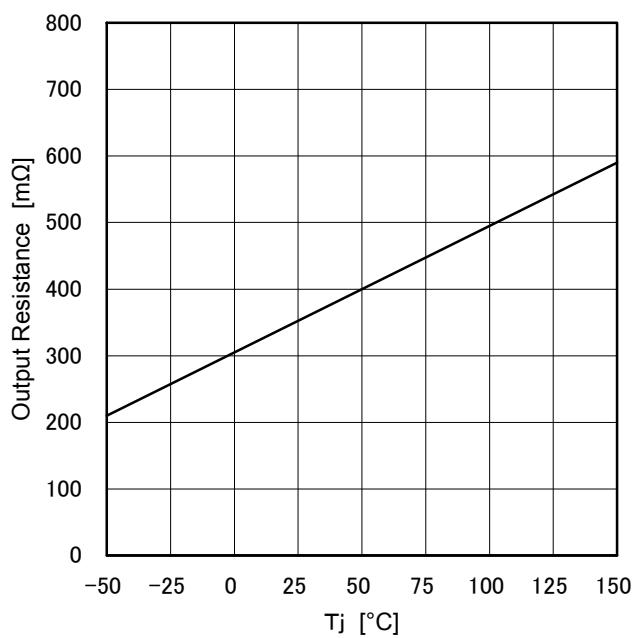


Figure 6. Output ON Resistance Characteristic  
[Temperature Characteristic]

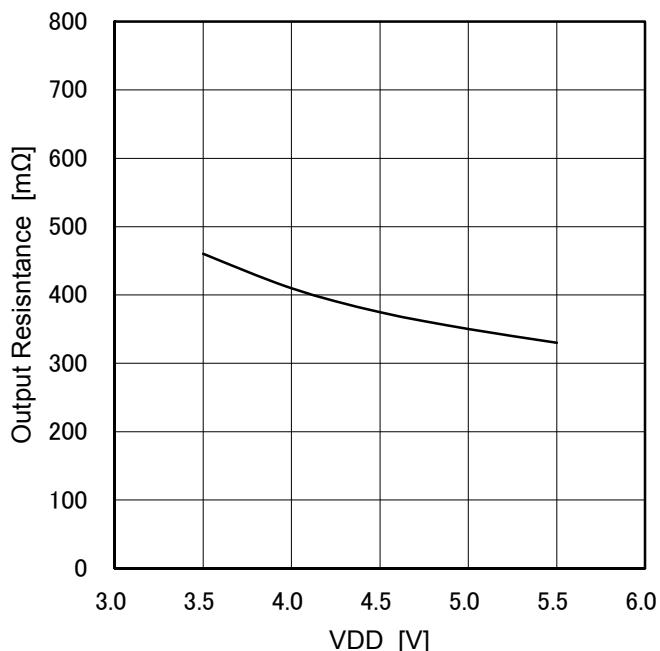


Figure 7. Output ON Resistance Characteristic  
[Source Voltage Characteristic]

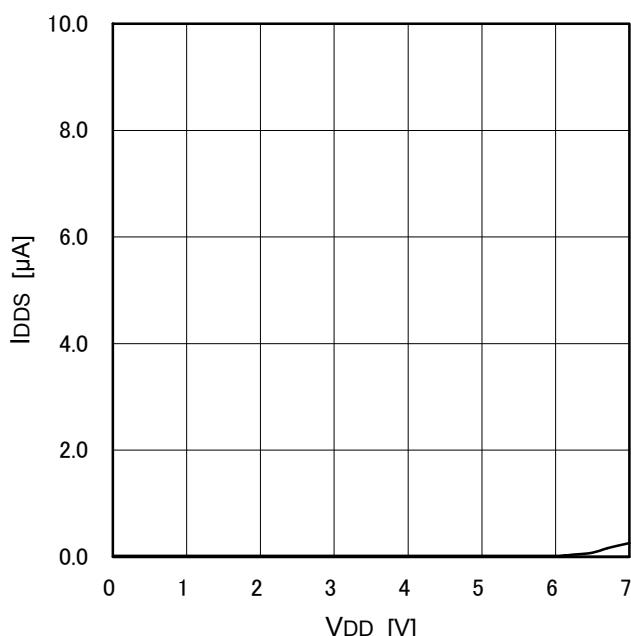


Figure 8. Standby Current Characteristic  
[Source Voltage Characteristic]

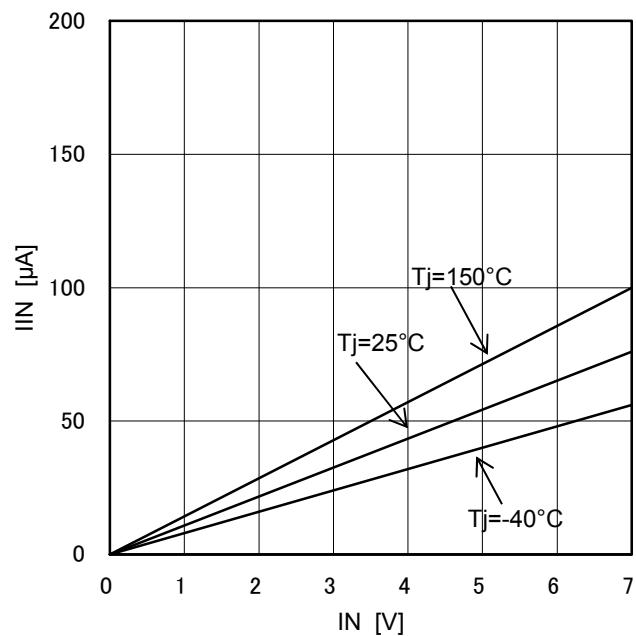


Figure 9. Input Current Characteristic  
[Input Voltage Characteristic]

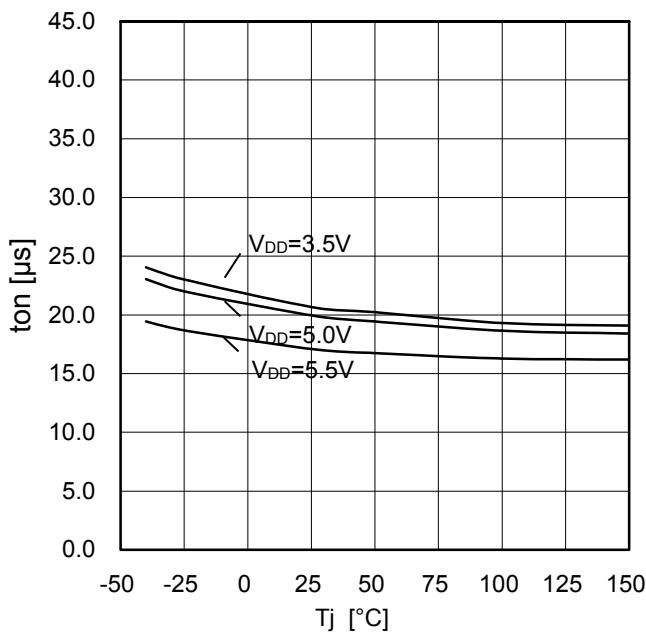


Figure 10. Switching Time ( $t_{on}$ ) [Temperature Characteristic]

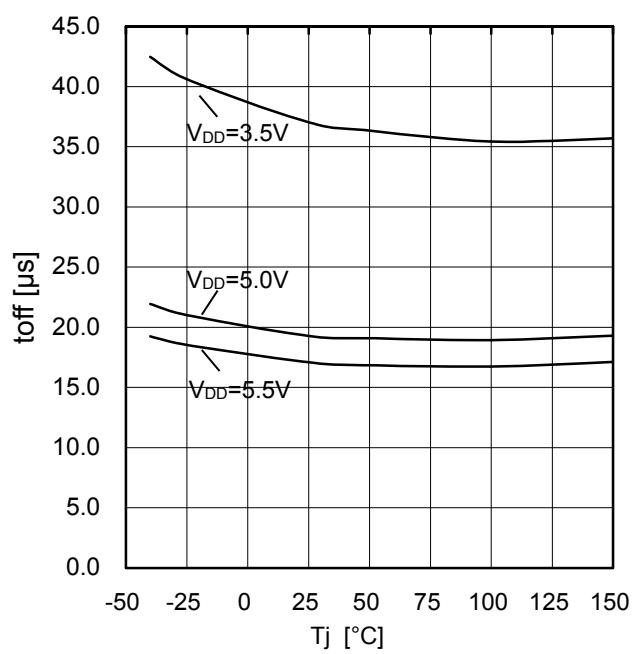


Figure 11. Switching Time ( $t_{off}$ ) [Temperature Characteristic]

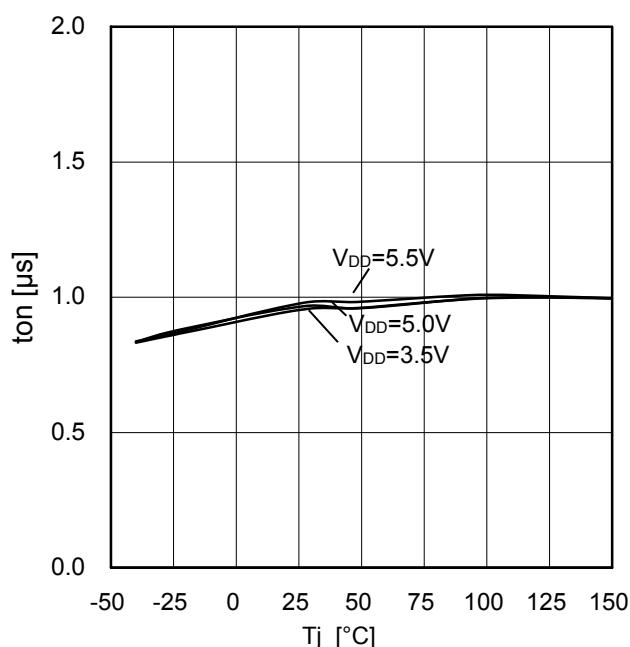


Figure 12. Slew Rate (at ON) [Temperature Characteristic]

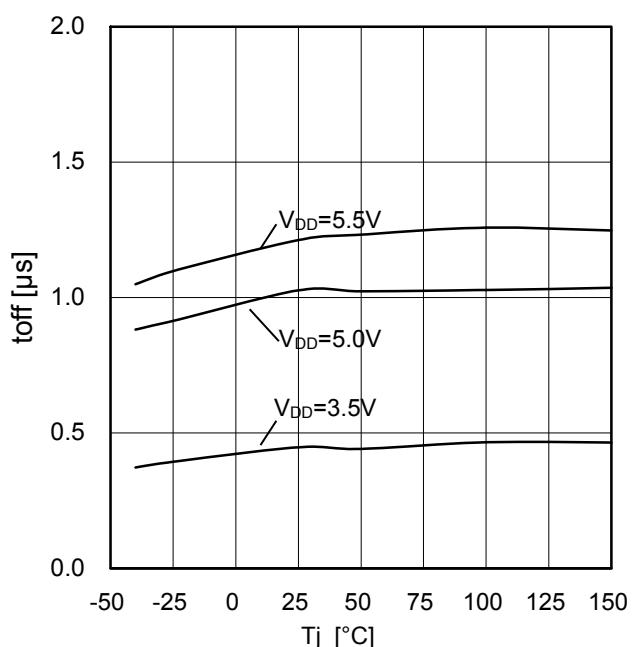


Figure 13. Slew Rate (at OFF) [Temperature Characteristic]

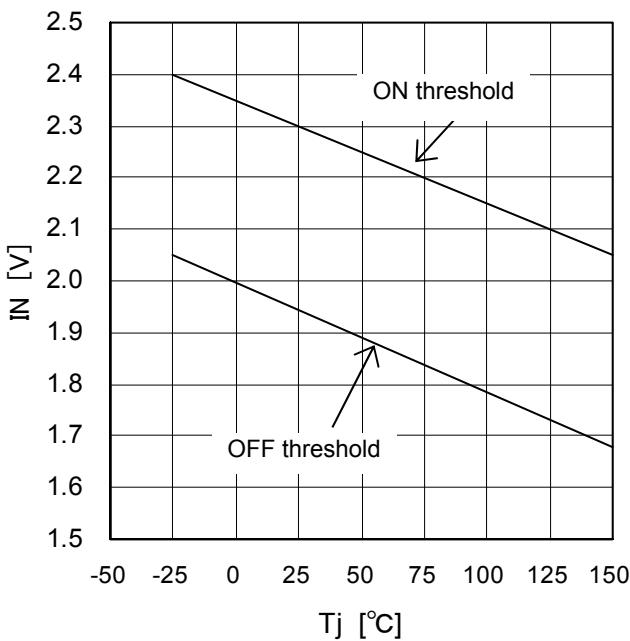


Figure 14. Input Voltage Threshold Characteristic  
[Temperature Characteristic]

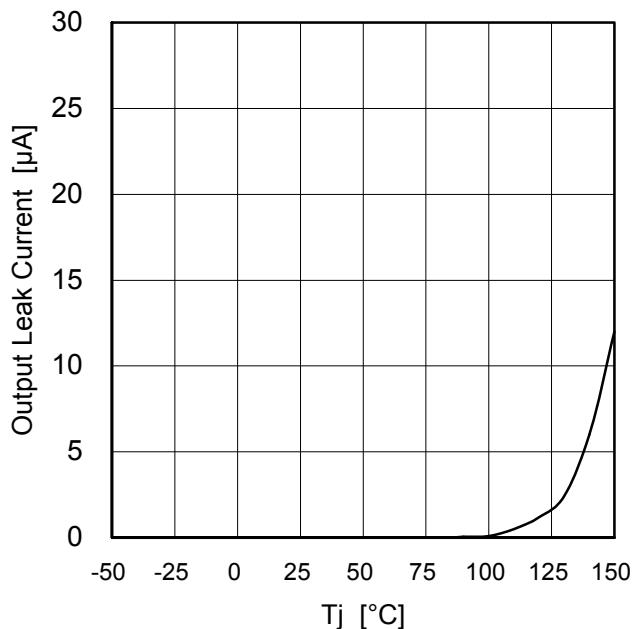


Figure 15. Output Leak Current [Temperature Characteristic]  
( $V_{IN}=0V$ )

### Switching Time Measurement

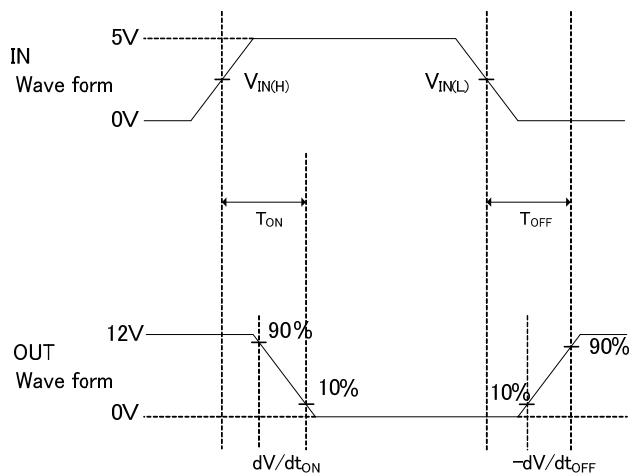


Figure 16. Switching Time

### Timing Chart with Inductive Load

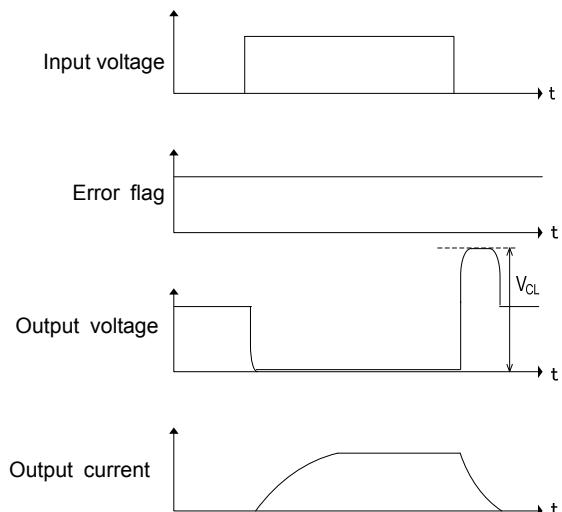


Figure 17. Timing Chart with Inductive Load

## Protective Function Timing Charts

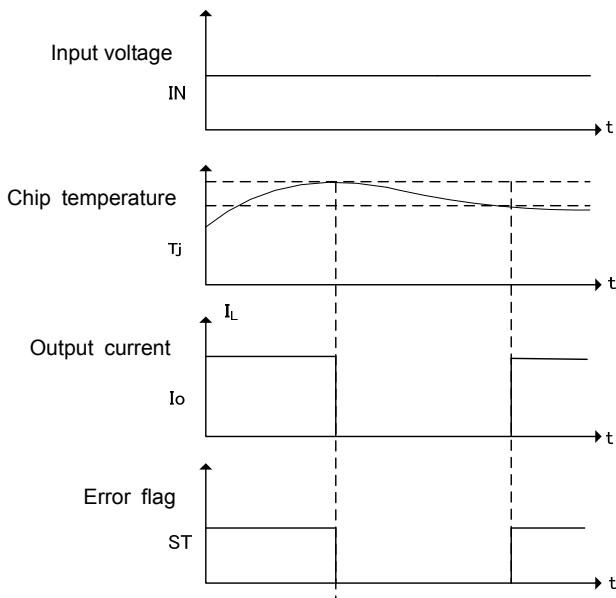


Figure 18. Overheat Protection Timing Chart

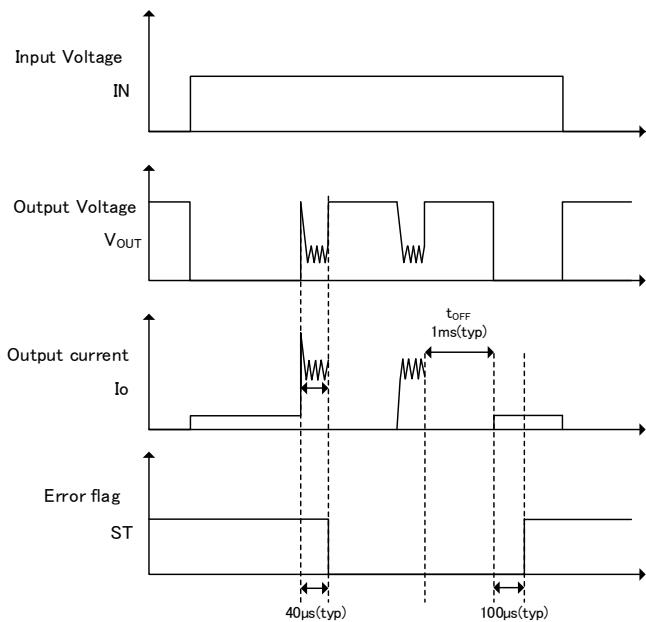


Figure 19. Overcurrent Protection Timing Chart

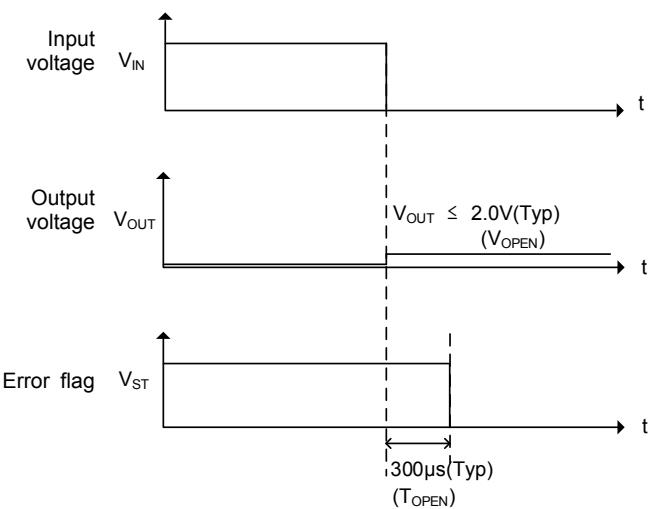
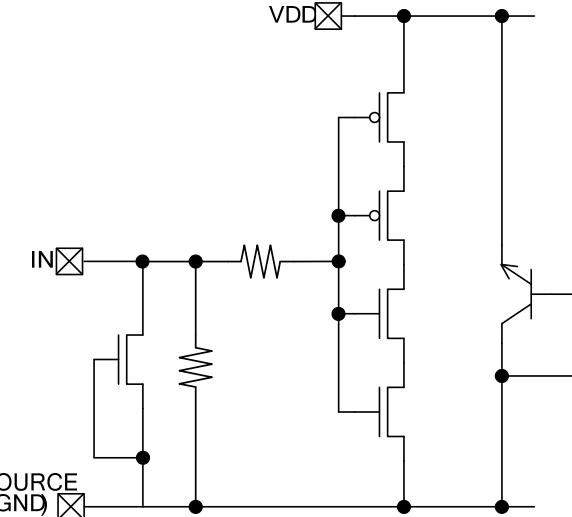
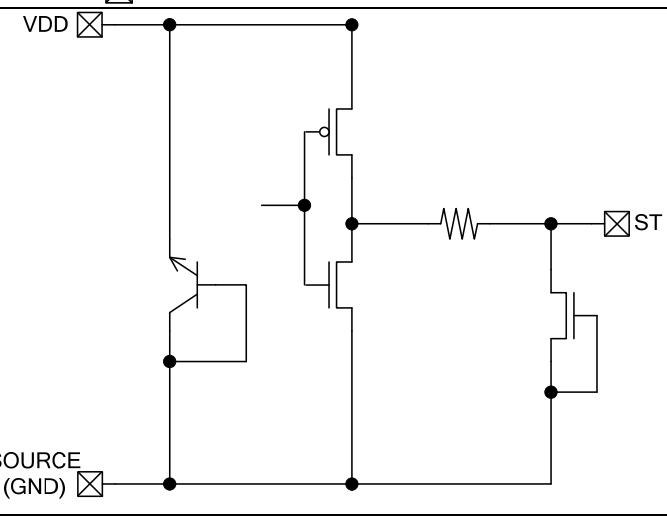
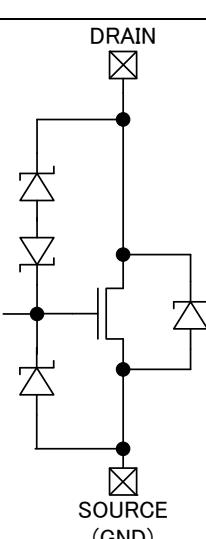


Figure 20. Open Detection Protection Timing Chart

## I/O Equivalent Circuits

Pin	Symbol	I/O Equivalent Circuits
1	IN	
2	ST	
3.4	SOURCE (GND)	
5,6	DRAIN	
8	VDD	
Cooling Tab	TAB	

## Ordering Information

B D 1 L B 5 0 0 E F J	-	CE2
PKG EFJ: HTSOP-J8		
B D 1 L B 5 0 0 F V M	-	CGTR
PKG FVM: MSOP8		

C: High reliability  
G: Manufacturing code  
Packaging and forming specification  
E2: Embossed tape and reel

C: High reliability  
G: Manufacturing code  
Packaging and forming specification  
TR: Embossed tape and reel

## Physical Dimension Tape and Reel Information

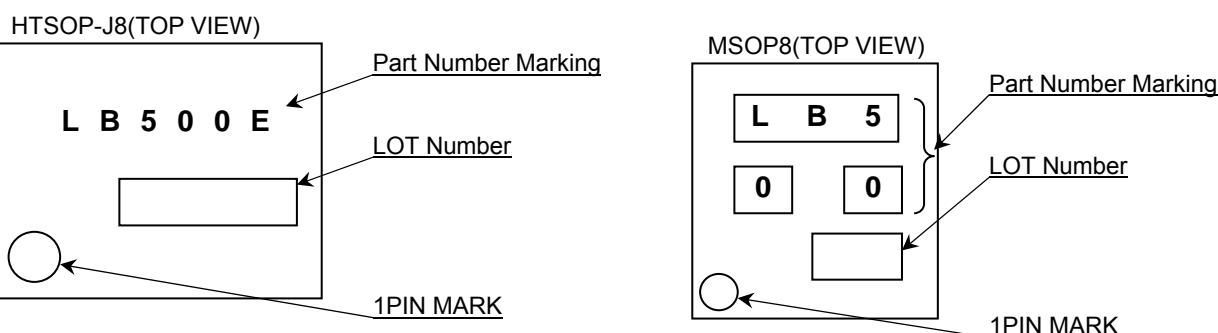
## HTSOP-J8

	<p><b>&lt;Tape and Reel information&gt;</b></p> <table border="1"> <tr><td>Tape</td><td>Embossed carrier tape</td></tr> <tr><td>Quantity</td><td>2500pcs</td></tr> <tr><td>Direction of feed</td><td>E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)</td></tr> </table> <p>1pin Reel Direction of feed</p> <p>*Order quantity needs to be multiple of the minimum quantity.</p>	Tape	Embossed carrier tape	Quantity	2500pcs	Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)
Tape	Embossed carrier tape						
Quantity	2500pcs						
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)						

## MSOP8

	<p><b>&lt;Tape and Reel information&gt;</b></p> <table border="1"> <tr><td>Tape</td><td>Embossed carrier tape</td></tr> <tr><td>Quantity</td><td>3000pcs</td></tr> <tr><td>Direction of feed</td><td>TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)</td></tr> </table> <p>1pin Reel Direction of feed</p> <p>*Order quantity needs to be multiple of the minimum quantity.</p>	Tape	Embossed carrier tape	Quantity	3000pcs	Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)
Tape	Embossed carrier tape						
Quantity	3000pcs						
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)						

## Marking Diagram



**Operational Notes**

## 1) Absolute Maximum Ratings

Operating the IC over the absolute maximum ratings may damage the IC. In addition, it is impossible to predict all destructive situations such as short-circuit modes or open circuit modes. Therefore, it is important to consider circuit protection measures, like adding a fuse, in case the IC is expected to be operated in a special mode exceeding the absolute maximum ratings.

## 2) Reverse connection of power supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply terminals.

## 3) Power supply lines

Design the PCB layout pattern to provide low impedance ground and supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

## 4) Source (GND) Voltage

The voltage of the Source (GND) pin must be the lowest voltage of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.

## 5) Thermal consideration

Use a thermal design that allows for a sufficient margin by taking into account the permissible power dissipation ( $P_d$ ) in actual operating conditions. Consider  $P_c$  that does not exceed  $P_d$  in actual operating conditions ( $P_c \geq P_d$ ).

Package Power dissipation :  $P_d (W) = (T_{jmax} - T_a) / \theta_{ja}$

Power dissipation :  $P_c (W) = (V_{cc} - V_o) \times I_o + V_{cc} \times I_b$

$T_{jmax}$  : Maximum junction temperature=150°C,  $T_a$  : Peripheral temperature[°C],

$\theta_{ja}$  : Thermal resistance of package-ambience[°C/W],  $P_d$  : Package Power dissipation [W],

$P_c$  : Power dissipation [W],  $V_{cc}$  : Input Voltage,  $V_o$  : Output Voltage,  $I_o$  : Load,  $I_b$  : Bias Current

## 6) Short between pins and mounting errors

Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.

## 7) Thermal shutdown circuit (TSD)

The IC incorporates a built-in thermal shutdown circuit, which is designed to turn off the IC when the internal temperature of the IC reaches 175°C (25°C hysteresis). It is not designed to protect the IC from damage or guarantee its operation. Do not continue to operate the IC after this function is activated. Do not use the IC in conditions where this function will always be activated.

## 8) Over voltage protection (active clamp)

There is a built-in over voltage protection circuit (active clamp) to absorb the induced current when inductive load is off (Power MOS = off). During active clamp and when IN=0V, TSD will not function so keep IC temperature below 150°C.

## 9) Over current protection circuit (OCP)

The IC incorporates an over-current protection circuit that operates in accordance with the rated output capacity. This circuit protects the IC from damage when the load becomes shorted. It is also designed to limit the output current (without latching) in the event of more than 1.5A (typ) flow, such as from a large capacitor or other component connected to the output pin. This protection circuit is effective in preventing damage to the IC in cases of sudden and unexpected current surges. The IC should not be used in applications where the over current protection circuit will be activated continuously.

## 10) Testing on application boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

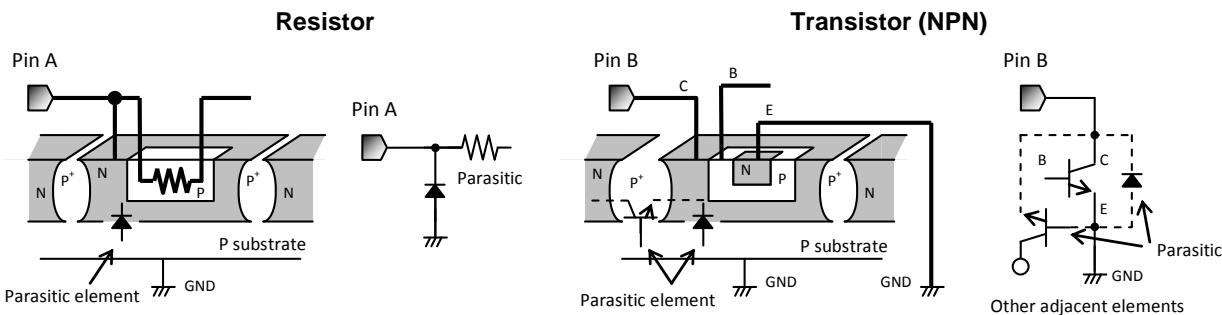
## 11) Regarding input pins of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.

When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.



Example of monolithic IC structure

12) GND wiring pattern

When using both small-signal and large-current GND traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the GND traces of external components do not cause variations on the GND voltage. The power supply and ground lines must be as short and thick as possible to reduce line impedance.

13) Back electromotive force (BEMF)

There is a possibility that the BEMF is changed by using the operating condition, environment and the individual characteristics of motor. Please make sure there is no problem when operating the IC even though the BEMF is changed.

14) Rush Current

When power is supplied to the IC, inrush current may flow instantaneously. It is possible that the charge current from the parasitic capacitance of the internal logic may be unstable. Therefore, give a special consideration with the power coupling capacitance, power wiring, width of GND wiring, and routing of connections.

15) TAB

IC's sub is already connected to TAB, please short TAB to External GND.

## Revision History

Date	Revision	Changes
01.Aug.2013	003	New release
06.Aug.2013	004	• P.11 Figure20 $V_{OUT}$ timing chart is modified.
10.Jan.2014	005	• P4. Condition of Diagnostic output voltage "L level" is added. • P4. Item of Diagnostic output voltage "H level" is added.
1.Apr.2015	006	• P1. "AEC-Q100 qualified" is added in Features • P1. Note (1),(2) and (3) are added • P2. Pin No 7 N.C. is added in Pin Description • P2. "Cooling Tab"(Symbol; TAB) is added in Pin Description • P3. Note (6) is added • P4. Min of " Diagnostic output voltage "H level" " is changed to 4.88V • P9. "ton" is changed to "toff" in Figure 11. 13. • P10. Figure 17 is changed • P15. FIN is changed to TAB in 15)
10.Nov.2015	007	• P3. "Absolute Maximum Ratings" Note (5) is changed • P3. "Heat Dissipation Characteristics" Note(3) is changed
26.May.2017	008	• P1. "Basic Application Circuit(Recommendation)" Comment of note (3) is added • P3. Active clamp energy (single pulse) limit value of $T_j(0)=150^{\circ}\text{C}$ is added in "Absolute Maximum Ratings". • P13. Revised expression on the information of Ordering Information.

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	
CLASS IV		CLASS III	CLASS III

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  - [h] Use of the Products in places subject to dew condensation
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8. Confirm that operation temperature is within the specified range described in the product specification.
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For details, please refer to ROHM Mounting specification

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